28C64A

64K (8K x 8) CMOS EEPROM

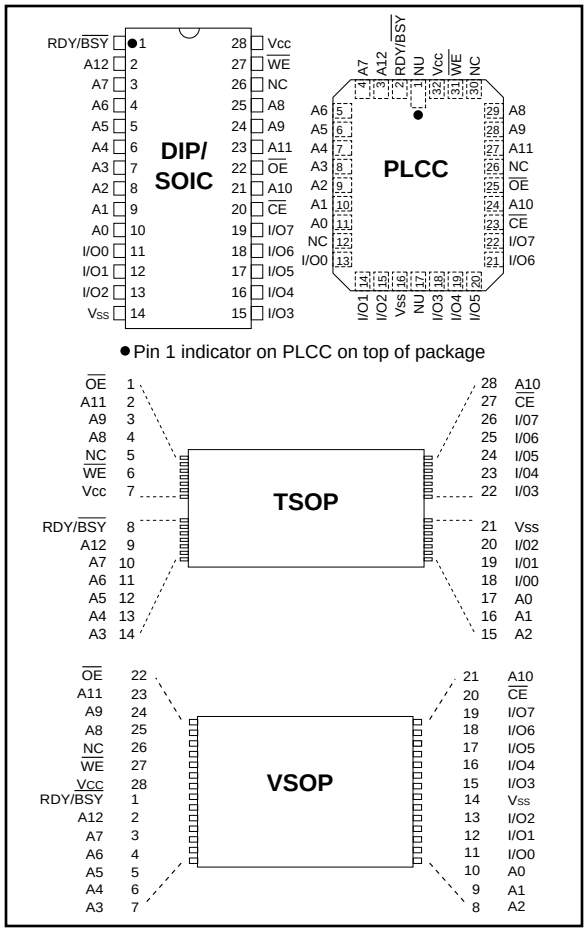
FEATURES

- Fast Read Access Time—150 ns
- CMOS Technology for Low Power Dissipation
  - 30 mA Active
  - 100 µA Standby
- Fast Byte Write Time—200 µs or 1 ms
- Data Retention >200 years
- High Endurance - Minimum 100,000 Erase/Write Cycles
- Automatic Write Operation
  - Internal Control Timer
  - Auto-Clear Before Write Operation
  - On-Chip Address and Data Latches
- $\overline{\text{Data}}$ Polling
- Ready/$\overline{\text{Busy}}$
- Chip Clear Operation
- Enhanced Data Protection
  - V_{CC} Detector
  - Pulse Filter
  - Write Inhibit
- Electronic Signature for Device Identification
- 5-Volt-Only Operation
- Organized 8Kx8 JEDEC Standard Pinout
  - 28-pin Dual-In-Line Package
  - 32-pin PLCC Package
  - 28-pin Thin Small Outline Package (TSOP) 8x20mm
  - 28-pin Very Small Outline Package (VSOP) 8x13.4mm
- Available for Extended Temperature Ranges:
  - Commercial: 0˚C to +70˚C

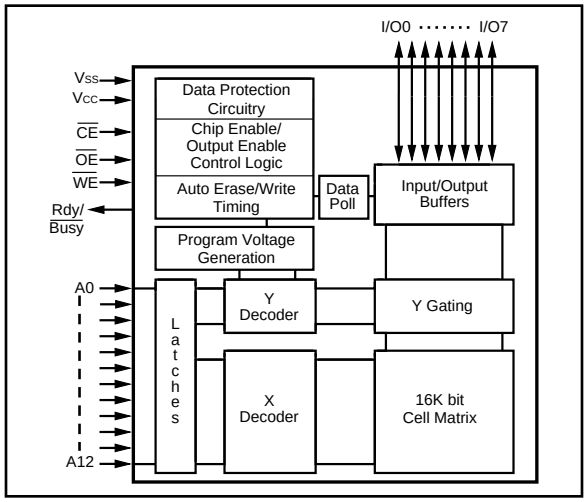
DESCRIPTION

The Microchip Technology Inc. 28C64A is a CMOS 64K non-volatile electrically Erasable PROM. The 28C64A is accessed like a static RAM for the read or write cycles without the need of external components. During a “byte write”, the address and data are latched internally, freeing the microprocessor address and data bus for other operations. Following the initiation of write cycle, the device will go to a busy state and automatically clear and write the latched data using an internal control timer. To determine when the write cycle is complete, the user has a choice of monitoring the Ready/$\overline{\text{Busy}}$ output or using $\overline{\text{Data}}$ polling. The Ready/$\overline{\text{Busy}}$ pin is an open drain output, which allows easy configuration in wired-or systems. Alternatively, $\overline{\text{Data}}$ polling allows the user to read the location last written to when the write operation is complete. CMOS design and processing enables this part to be used in systems where reduced power consumption and reliability are required. A complete family of packages is offered to provide the utmost flexibility in applications

PACKAGE TYPE



BLOCK DIAGRAM



1.0 ELECTRICAL CHARACTERISTICS

1.1 MAXIMUM RATINGS*

V_{CC} and input voltages w.r.t. V_{SS}..... -0.6V to + 6.25V

Voltage on $\overline{OE}$ w.r.t. V_{SS} ..... -0.6V to +13.5V

Voltage on A9 w.r.t. V_{SS} ..... -0.6V to +13.5V

Output Voltage w.r.t. V_{SS}.....-0.6V to V_{CC}+0.6V

Storage temperature .....-65˚C to +125˚C

Ambient temp. with power applied .....-50˚C to +95˚C

***Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 1-1: PIN FUNCTION TABLE

Name	Function
A0 - A12	Address Inputs
$\overline{CE}$	Chip Enable
$\overline{OE}$	Output Enable
$\overline{WE}$	Write Enable
I/O0 - I/O7	Data Inputs/Outputs
RDY/$\overline{Busy}$	Ready/$\overline{Busy}$
V_{CC}	+5V Power Supply
V_{SS}	Ground
NC	No Connect; No Internal Connection
NU	Not Used; No External Connection is Allowed

TABLE 1-2: READ/WRITE OPERATION DC CHARACTERISTIC

				V_{CC} = +5V ±10% Commercial (C): Tamb = 0˚C to +70˚C Industrial (I): Tamb = -40˚C to +85˚C		
Parameter	**Status**	**Symbol**	**Min**	**Max**	**Units**	**Conditions**
Input Voltages	Logic ‘1’ Logic ‘0’	V_{IH} V_{IL}	2.0 -0.1	Vcc+1 0.8	V V	
Input Leakage	—	I_{LI}	-10	10	µA	V_{IN} = -0.1V to Vcc +1
Input Capacitance	—	C_{IN}	—	10	pF	V_{IN} = 0V; Tamb = 25˚C; f = 1 MHz (Note 2)
Output Voltages	Logic ‘1’ Logic ‘0’	V_{OH} V_{OL}	2.4	 0.45	V V	I_{OH} = -400 µA I_{OL} = 2.1 mA
Output Leakage	—	I_{LO}	-10	10	µA	V_{OUT} = -0.1V to Vcc +0.1V
Output Capacitance	—	C_{OUT}	—	12	pF	V_{IN} = 0V; Tamb = 25˚C; f = 1 MHz (Note 2)
Power Supply Current, Active	TTL input	I_{CC}	—	30	mA	f = 5 MHz (Note 1) V_{CC} = 5.5V
Power Supply Current, Standby	TTL input TTL input CMOS input	$I_{CC(S)TTL}$ $I_{CC(S)TTL}$ $I_{CC(S)CMOS}$	—	2 3 100	mA mA µA	$\overline{CE}$ = V_{IH} (0˚C to +70˚C) $\overline{CE}$ = V_{IH} (-40˚C to +85˚C) $\overline{CE}$ = V_{CC}-0.3 to Vcc +1

Note 1: AC power supply current above 5MHz: 2mA/MHz.
Note 2: Not 100% tested.

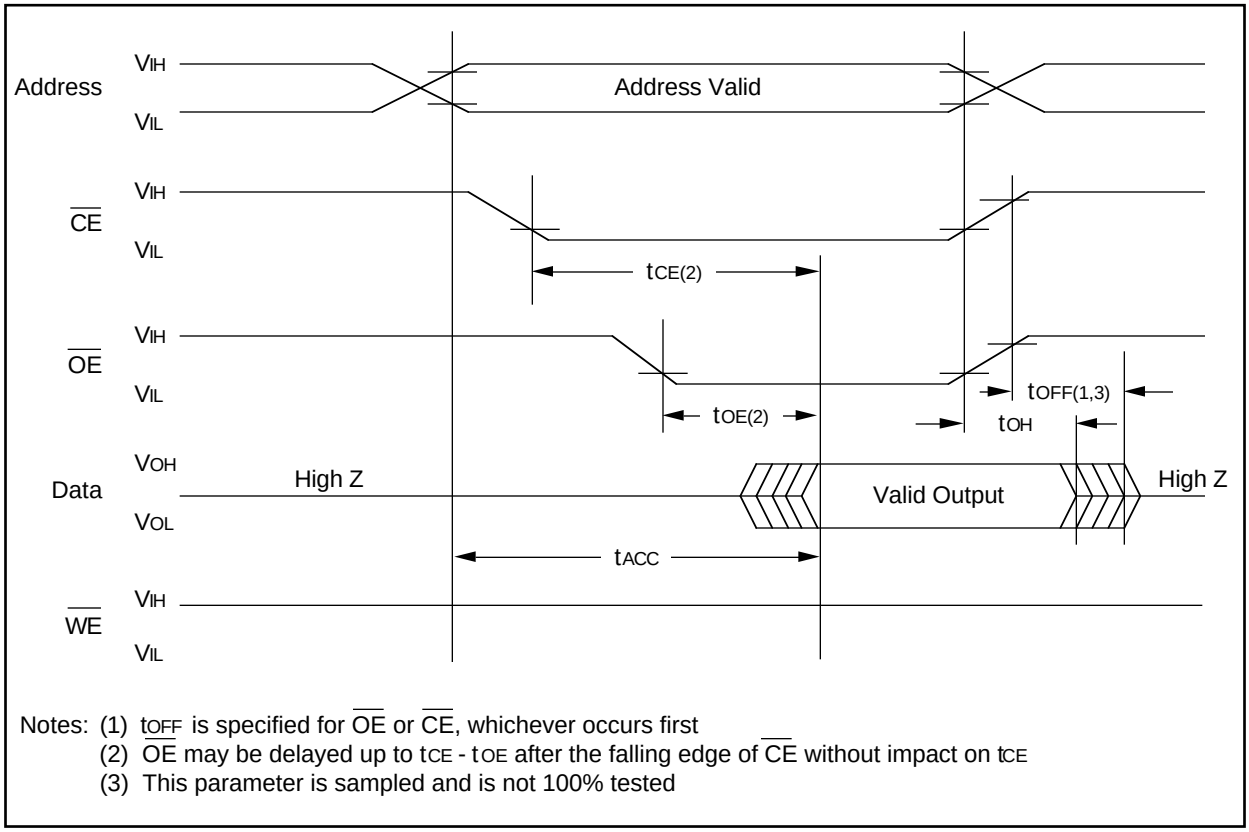
TABLE 1-3: READ OPERATION AC CHARACTERISTICS

AC Testing Waveform:	V_{IH} = 2.4V; V_{IL} = 0.45V; V_{OH} = 2.0V; V_{OL} = 0.8V	
Output Load:	1 TTL Load + 100 pF	
Input Rise and Fall Times:	20 ns	
Ambient Temperature:	Commercial (C):	Tamb = 0°C to +70°C
	Industrial (I):	Tamb = -40°C to +85°C

Parameter	Symbol	28C64A-15		28C64A-20		28C64A-25		Units	Conditions
		Min	Max	Min	Max	Min	Max		
Address to Output Delay	t_{ACC}	—	150	—	200	—	250	ns	$\overline{OE}$ = $\overline{CE}$ = V_{IL}
$\overline{CE}$ to Output Delay	t_{CE}	—	150	—	200	—	250	ns	$\overline{OE}$ = V_{IL}
$\overline{OE}$ to Output Delay	t_{OE}	—	70	—	80	—	100	ns	$\overline{CE}$ = V_{IL}
$\overline{CE}$ or $\overline{OE}$ High to Output Float	t_{OFF}	0	50	0	55	0	70	ns	Note 1
Output Hold from Address, $\overline{CE}$ or $\overline{OE}$, whichever occurs first.	t_{OH}	0	—	0	—	0	—	ns	Note 1

Note 1: Not 100% tested.

FIGURE 1-1: READ WAVEFORMS



Notes: (1) t_{OFF} is specified for $\overline{OE}$ or $\overline{CE}$, whichever occurs first
(2) $\overline{OE}$ may be delayed up to t_{CE} - t_{OE} after the falling edge of $\overline{CE}$ without impact on t_{CE}
(3) This parameter is sampled and is not 100% tested

TABLE 1-4: BYTE WRITE AC CHARACTERISTICS

	AC Testing Waveform:		V_{IH} = 2.4V; V_{IL} = 0.45V; V_{OH} = 2.0V; V_{OL} = 0.8V		
	Output Load:		1 TTL Load + 100 pF		
	Input Rise/Fall Times:		20 ns		
	Ambient Temperature:		Commercial (C): Tamb = 0˚C to +70˚C Industrial (I): Tamb = -40˚C to +85˚C		
Parameter	**Symbol**	**Min**	**Max**	**Units**	**Remarks**
Address Set-Up Time	t_{AS}	10	—	ns	
Address Hold Time	t_{AH}	50	—	ns	
Data Set-Up Time	t_{DS}	50	—	ns	
Data Hold Time	t_{DH}	10	—	ns	
Write Pulse Width	t_{WPL}	100	—	ns	Note 1
Write Pulse High Time	t_{WPH}	50	—	ns	
$\overline{OE}$ Hold Time	t_{OEH}	10	—	ns	
$\overline{OE}$ Set-Up Time	t_{OES}	10	—	ns	
Data Valid Time	t_{DV}	—	1000	ns	Note 2
Time to Device Busy	t_{DB}	2	50	ns	
Write Cycle Time (28C64A)	t_{WC}	—	1	ms	0.5 ms typical
Write Cycle Time (28C64AF)	t_{WC}	—	200	µs	100 µs typical

Note 1: A write cycle can be initiated be $\overline{CE}$ or $\overline{WE}$ going low, whichever occurs last. The data is latched on the positive edge $\overline{WE}$, whichever occurs first.

Note 2: Data must be valid within 1000ns max. after a write cycle is initiated and must be stable at least until t_{DH} after the positive edge of $\overline{WE}$ or $\overline{CE}$, whichever occurs first.

FIGURE 1-2: PROGRAMMING WAVEFORMS

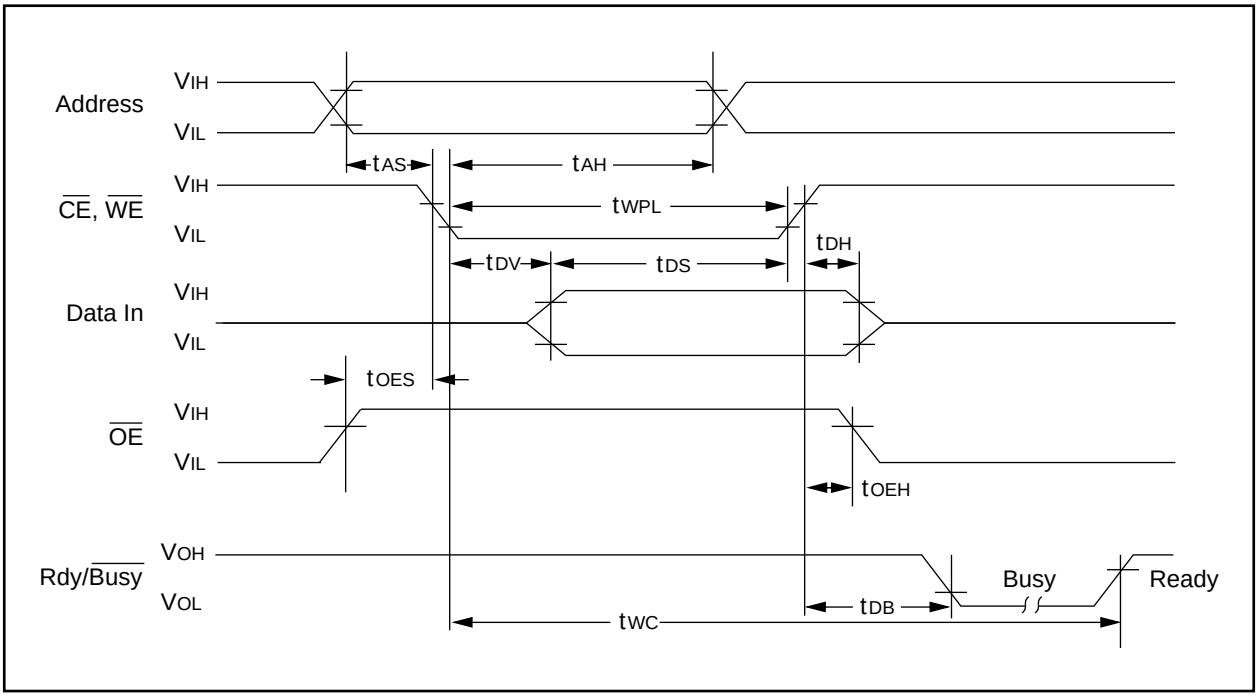


FIGURE 1-3: $\overline{\text{DATA}}$ POLLING WAVEFORMS

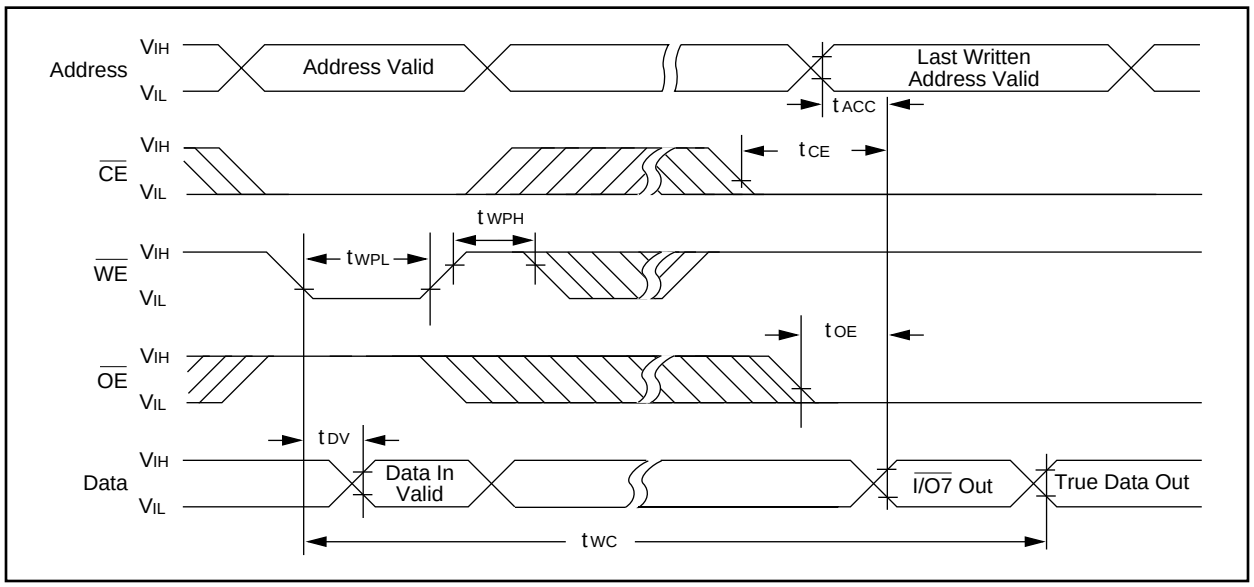


FIGURE 1-4: CHIP CLEAR WAVEFORMS

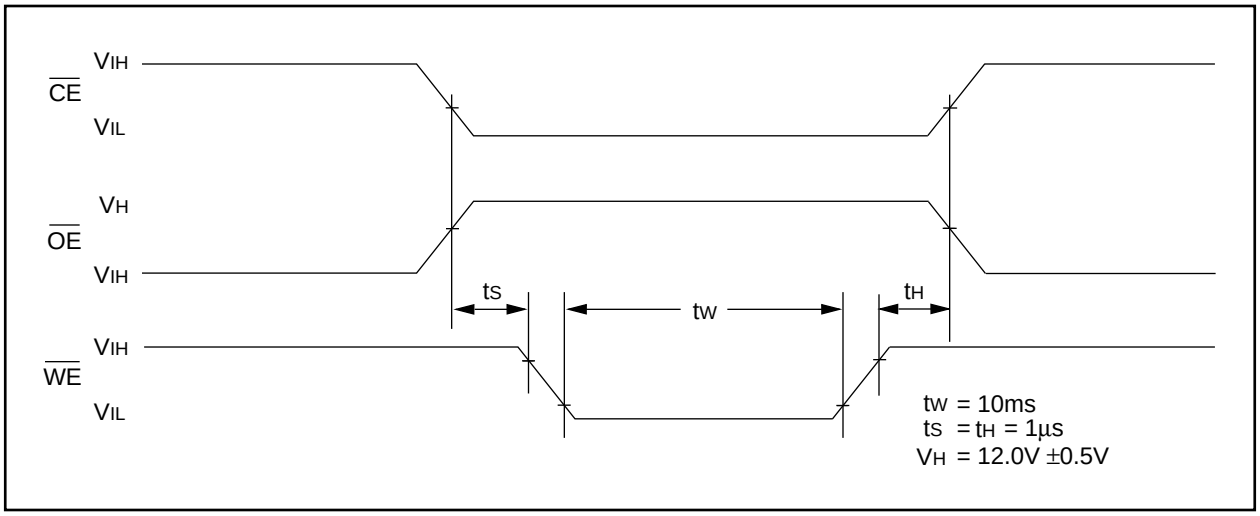


TABLE 1-5: SUPPLEMENTARY CONTROL

Mode	$\overline{\text{CE}}$	$\overline{\text{OE}}$	$\overline{\text{WE}}$	A9	Vcc	I/Oı
Chip Clear	VIL	VIH	VIL	X	Vcc	
Extra Row Read	VIL	VIL	VIH	A9 = VH	Vcc	Data Out
Extra Row Write	*	VIH	*	A9 = VH	Vcc	Data In

Note: VH = 12.0V±0.5V. *Pulsed per programming waveforms.

2.0 DEVICE OPERATION

The Microchip Technology Inc. 28C64A has four basic modes of operation—read, standby, write inhibit, and byte write—as outlined in the following table.

Operation Mode	$\overline{CE}$	$\overline{OE}$	$\overline{WE}$	I/O	Rdy/$\overline{Busy}$ (1)
Read	L	L	H	DOUT	H
Standby	H	X	X	High Z	H
Write Inhibit	H	X	X	High Z	H
Write Inhibit	X	L	X	High Z	H
Write Inhibit	X	X	H	High Z	H
Byte Write	L	H	L	DIN	L
Byte Clear	Automatic Before Each “Write”				

Note 1: Open drain output.
Note 2: X = Any TTL level.

2.1 Read Mode

The 28C64A has two control functions, both of which must be logically satisfied in order to obtain data at the outputs. Chip enable ($\overline{CE}$) is the power control and should be used for device selection. Output Enable ($\overline{OE}$) is the output control and is used to gate data to the output pins independent of device selection. Assuming that addresses are stable, address access time (tACC) is equal to the delay from $\overline{CE}$ to output (tCE). Data is available at the output tOE after the falling edge of $\overline{OE}$, assuming that $\overline{CE}$ has been low and addresses have been stable for at least tACC-tOE.

2.2 Standby Mode

The 28C64A is placed in the standby mode by applying a high signal to the $\overline{CE}$ input. When in the standby mode, the outputs are in a high impedance state, independent of the $\overline{OE}$ input.

2.3 Data Protection

In order to ensure data integrity, especially during critical power-up and power-down transitions, the following enhanced data protection circuits are incorporated:

First, an internal VCC detect (3.3 volts typical) will inhibit the initiation of non-volatile programming operation when VCC is less than the VCC detect circuit trip.

Second, there is a $\overline{WE}$ filtering circuit that prevents $\overline{WE}$ pulses of less than 10 ns duration from initiating a write cycle.

Third, holding $\overline{WE}$ or $\overline{CE}$ high or $\overline{OE}$ low, inhibits a write cycle during power-on and power-off (VCC).

2.4 Write Mode

The 28C64A has a write cycle similar to that of a Static RAM. The write cycle is completely self-timed and initiated by a low going pulse on the $\overline{WE}$ pin. On the falling edge of $\overline{WE}$, the address information is latched. On rising edge, the data and the control pins ($\overline{CE}$ and $\overline{OE}$) are latched. The Ready/$\overline{Busy}$ pin goes to a logic low level indicating that the 28C64A is in a write cycle which signals the microprocessor host that the system bus is free for other activity. When Ready/$\overline{Busy}$ goes back to a high, the 28C64A has completed writing and is ready to accept another cycle.

2.5 $\overline{Data}$ Polling

The 28C64A features $\overline{Data}$ polling to signal the completion of a byte write cycle. During a write cycle, an attempted read of the last byte written results in the data complement of I/O7 (I/O0 to I/O6 are indeterminable). After completion of the write cycle, true data is available. $\overline{Data}$ polling allows a simple read/compare operation to determine the status of the chip eliminating the need for external hardware.

2.6 Electronic Signature for Device Identification

An extra row of 32 bytes of EEPROM memory is available to the user for device identification. By raising A9 to 12V ±0.5V and using address locations 1FEO to 1FFF, the additional bytes can be written to or read from in the same manner as the regular memory array.

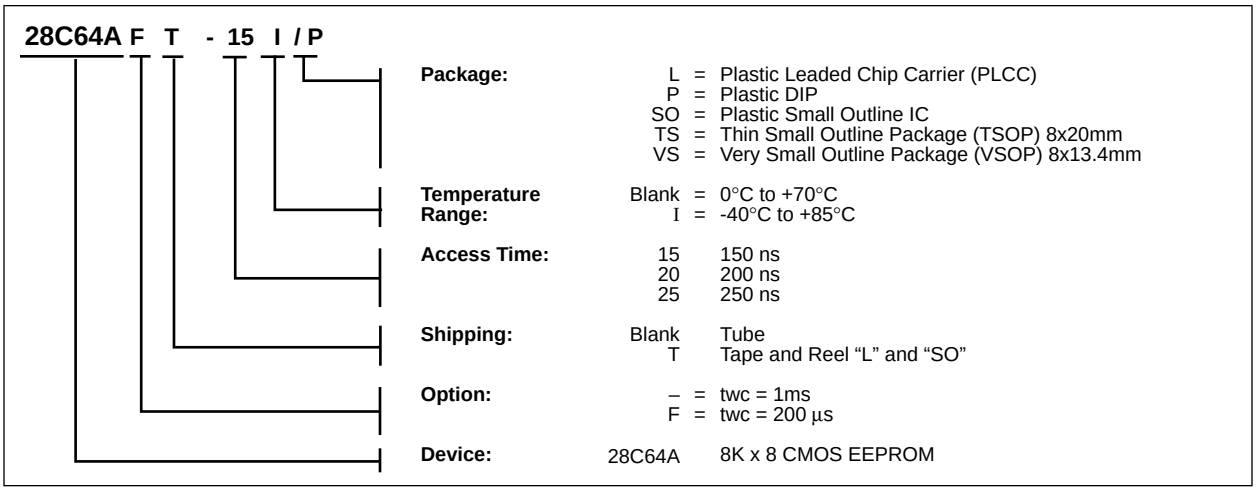
2.7 Chip Clear

All data may be cleared to 1's in a chip clear cycle by raising $\overline{OE}$ to 12 volts and bringing the $\overline{WE}$ and $\overline{CE}$ low. This procedure clears all data, except for the extra row.

NOTES

28C64A Product Identification System

To order or to obtain information, e.g., on pricing or delivery, please use the listed part numbers, and refer to the factory or the listed sales offices.



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9/5/95

MICROCHIP

Printed in the USA, 9/95